

Title (en)

METHOD FOR FORMING A METAL SIEVE MATERIAL, DEVICE FOR PERFORMING SAID METHOD AND METAL SIEVE MATERIAL FORMED

Publication

**EP 0252545 B1 19910522 (EN)**

Application

**EP 87201143 A 19870616**

Priority

NL 8601786 A 19860708

Abstract (en)

[origin: EP0252545A1] In a method for forming a sieve material a base sieve material is connected as a cathode in an electroplating bath; said bath contains an amount of a compound having properties of a second class brightener and during electrodeposition a flow of liquid is maintained through the perforations of the base sieve material. A thin deposit is allowed to form; said deposit is removed from the base sieve and thickened under essentially the same conditions in a further electroplating step. The thickened deposit has perforations of essentially the same size as the perforations in the base sieve material. The method may be carried out continuously. The invention concerns also a device for carrying out the method according to the invention.

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**C25D 1/08**

IPC 8 full level

**C25D 1/08** (2006.01); **C25D 7/00** (2006.01)

CPC (source: EP)

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Cited by

NL1021095C2; US5749287A; NL1021096C2; EP0603966A1; TR28431A; EP1714693A1; EP1323463A1; DE10037521C2; US7713397B2; EP1216087B1; WO2024068552A1; EP1542788B1; EP1885927B2

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